



SOT2111-1

HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body

15 September 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN148
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-04-2021
Manufacturer package code	98ASA01620D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.9	11	11.1	mm
package width	10.9	11	11.1	mm
package height	-	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	148	-	



HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body

2 Package outline

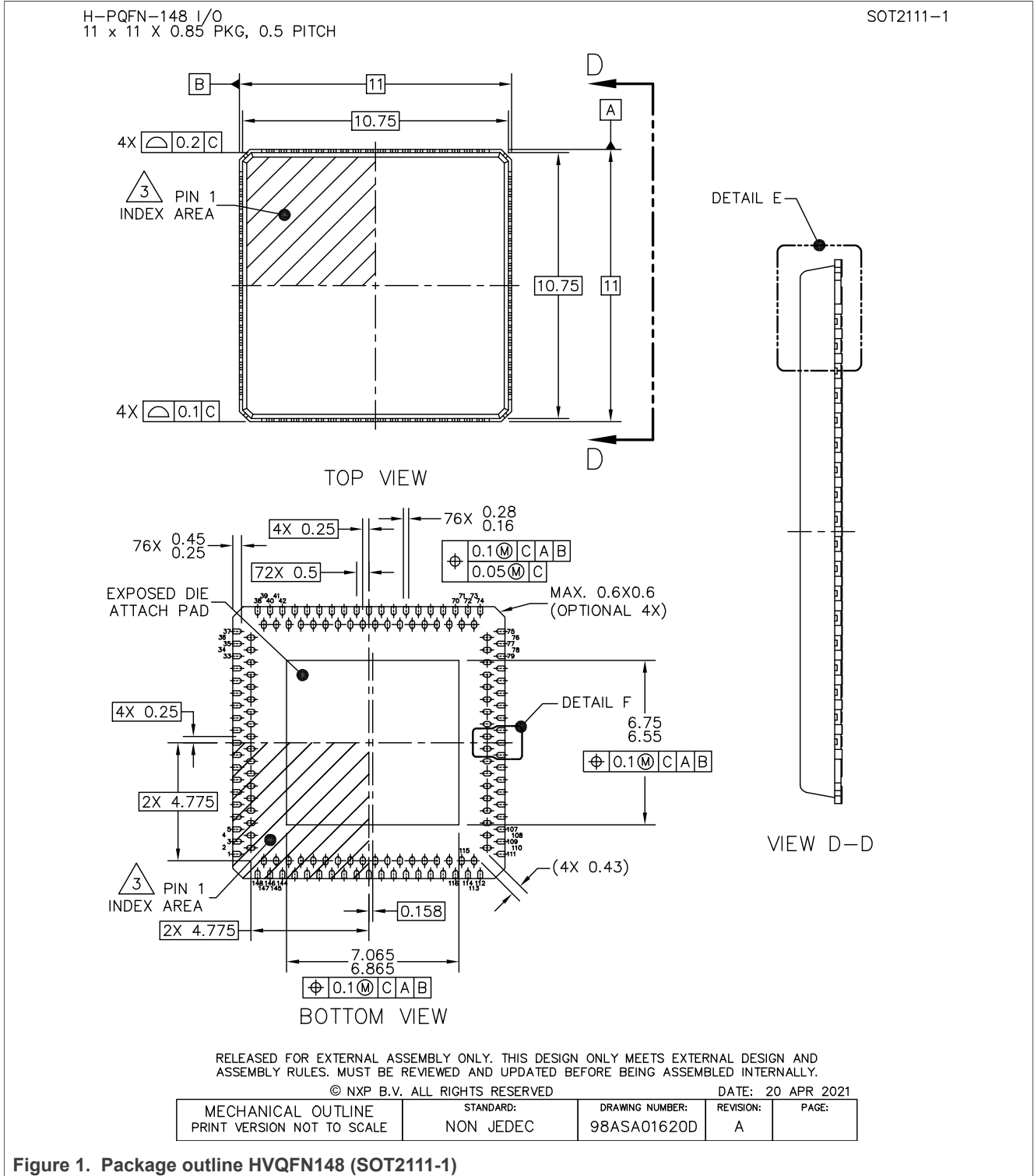
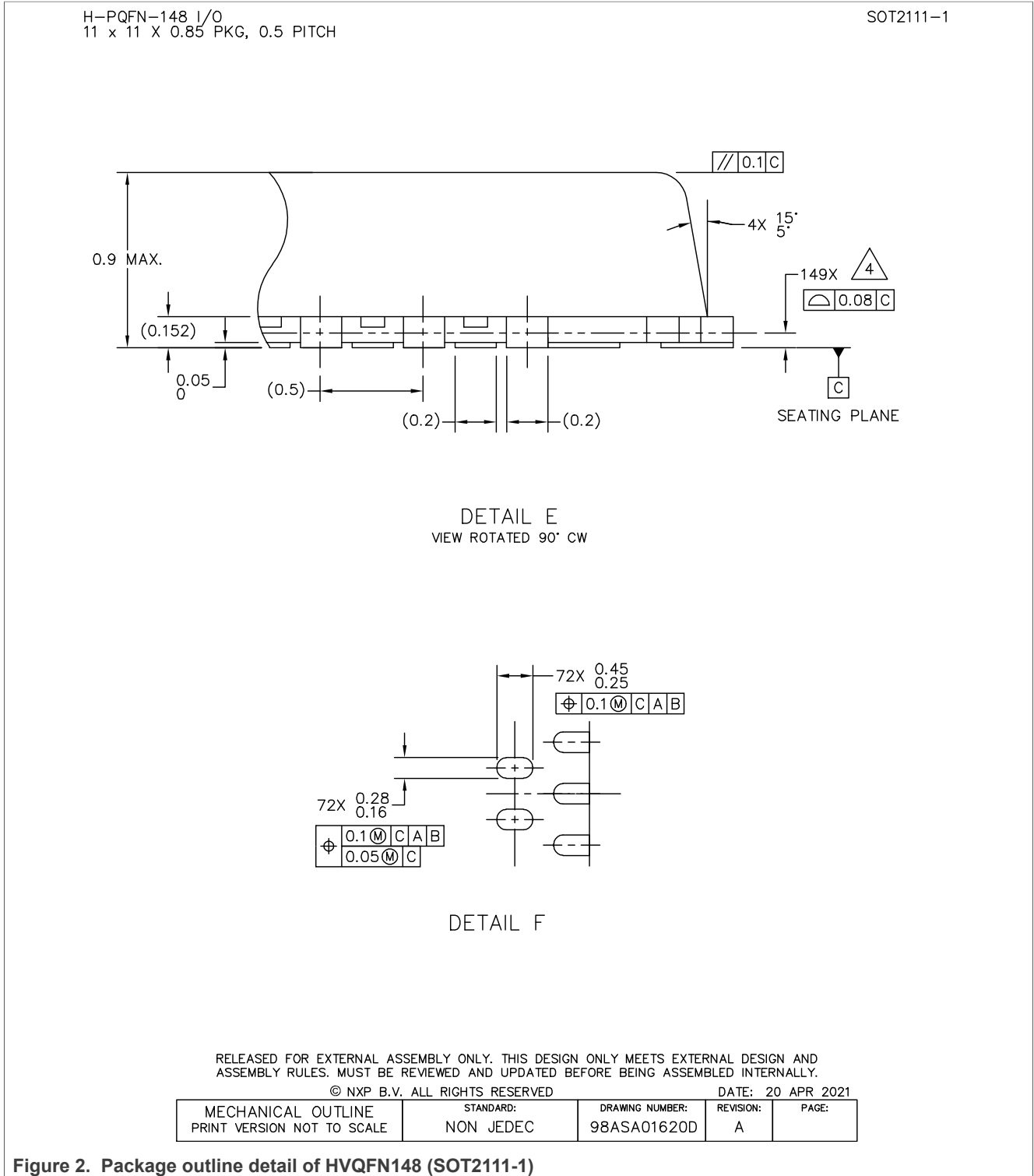


Figure 1. Package outline HVQFN148 (SOT2111-1)

HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body



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3 Soldering

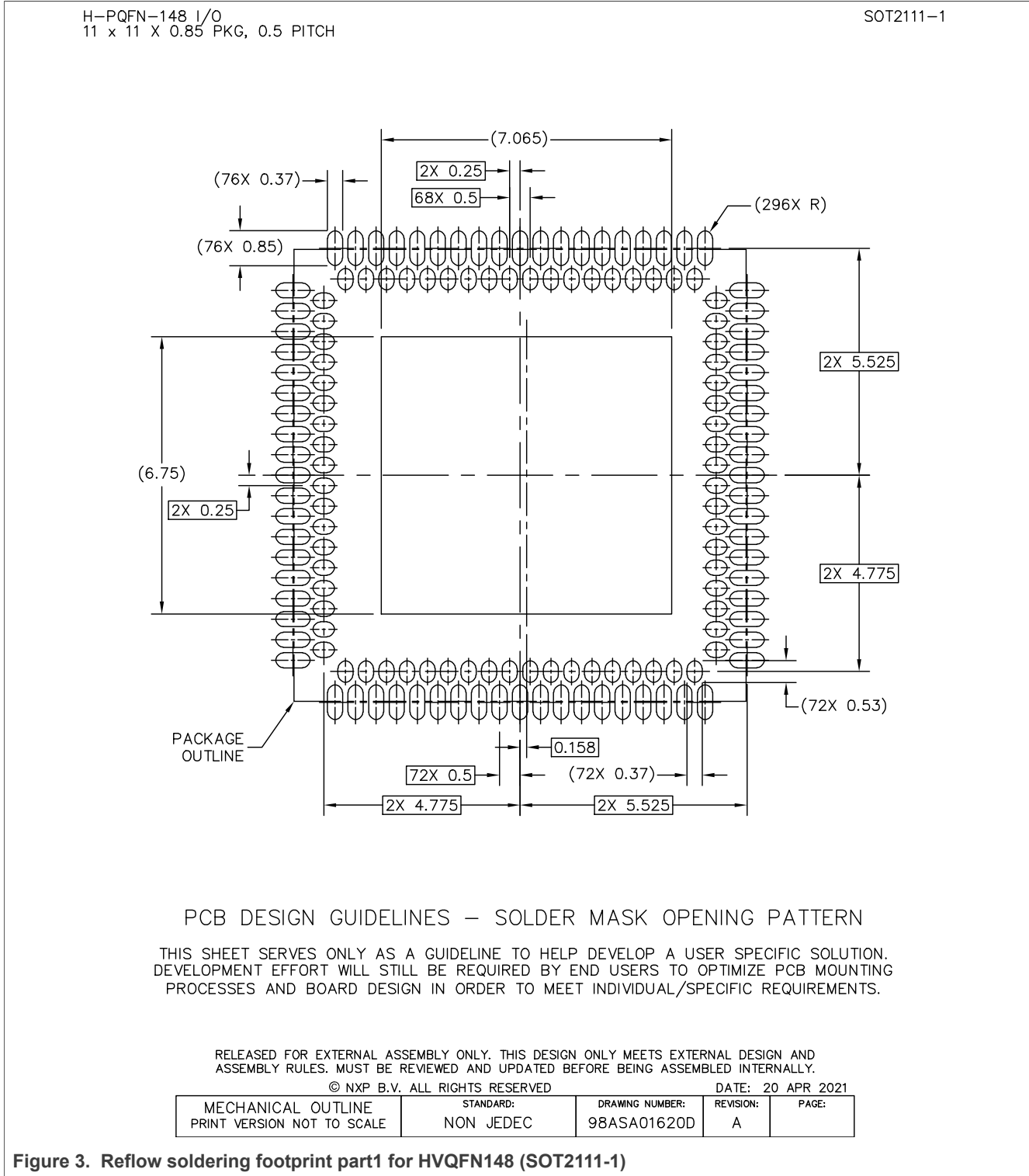


Figure 3. Reflow soldering footprint part1 for HVQFN148 (SOT2111-1)

HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body

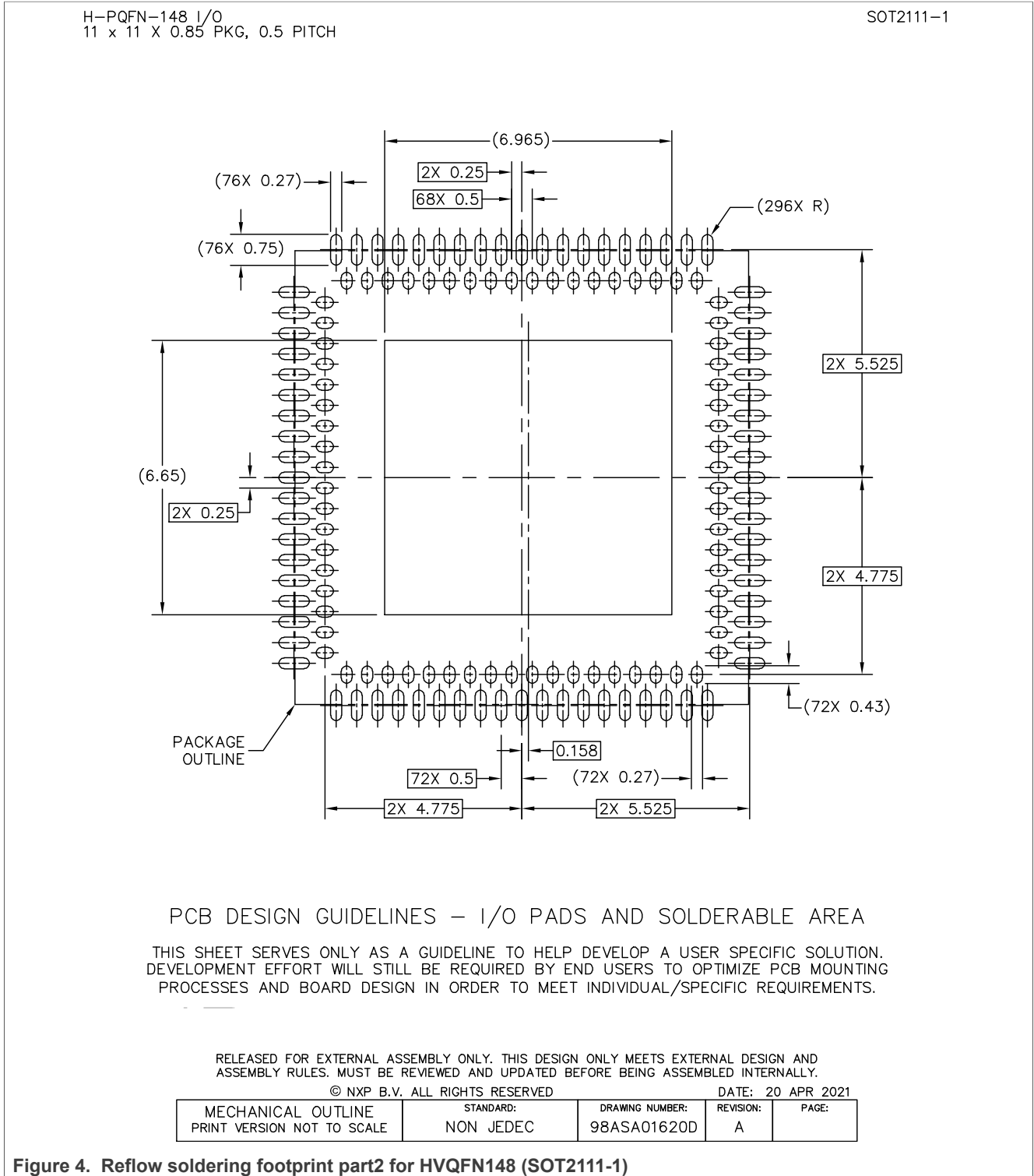
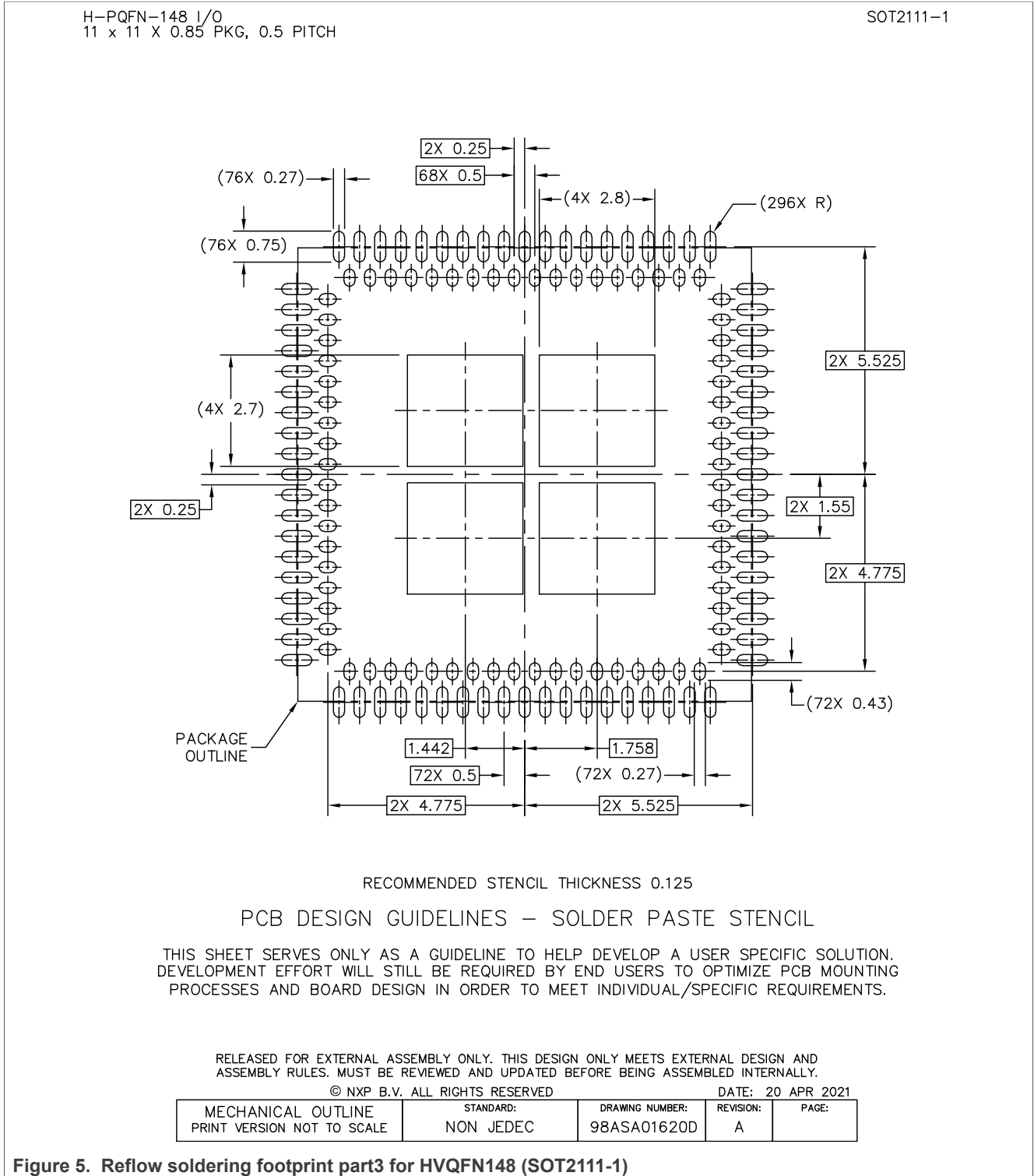


Figure 4. Reflow soldering footprint part2 for HVQFN148 (SOT2111-1)

HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body



HVQFN148, thermal enhanced very thin quad flat package, no leads, 148 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.85 mm body

H-PQFN-148 I/O
11 x 11 X 0.85 PKG, 0.5 PITCH

SOT2111-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

RELEASED FOR EXTERNAL ASSEMBLY ONLY. THIS DESIGN ONLY MEETS EXTERNAL DESIGN AND ASSEMBLY RULES. MUST BE REVIEWED AND UPDATED BEFORE BEING ASSEMBLED INTERNALLY.

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DATE: 20 APR 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01620D	REVISION: A	PAGE:
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Figure 6. Package outline note HVQFN148 (SOT2111-1)

4 Legal information

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